

NPN SURFACE MOUNT TRANSISTOR
Features

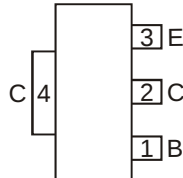
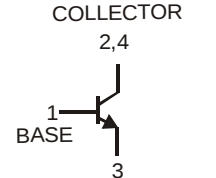
- Epitaxial Planar Die Construction
- Complementary PNP Type Available (DXTA92)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**

Mechanical Data

- Case: SOT89-3L
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish — Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking & Type Code Information: See Page 3
- Ordering Information: See Page 3
- Weight: 54.8mg (approximate)



Top View


 TOP VIEW
 Device Schematic


Pin Out Configuration

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CB0}	300	V
Collector-Emitter Voltage	V _{CE0}	300	V
Emitter-Base Voltage	V _{EBO}	6	V
Continuous Collector Current	I _C	500	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3) @ T _A = 25°C	P _D	1	W
Thermal Resistance, Junction to Ambient (Note 3)	R _{θJA}	125	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
OFF CHARACTERISTICS (Note 4)						
Collector-Base Breakdown Voltage	V _{(BR)CBO}	300	—	—	V	I _C = 100μA, I _E = 0
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	300	—	—	V	I _C = 1mA, I _B = 0
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	6	—	—	V	I _E = 100μA, I _C = 0
Collector Cut-off Current	I _{CBO}	—	—	0.1	μA	V _{CB} = 200V, I _E = 0
Emitter Cut-off Current	I _{EBO}	—	—	0.1	μA	V _{EB} = 6V, I _C = 0
ON CHARACTERISTICS (Note 4)						
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	—	—	0.5	V	I _C = 20mA, I _B = 2mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	—	—	0.9	V	I _C = 20mA, I _B = 2mA
Static Forward Current Transfer Ratio	h _{FE}	25 40 40	—	—	—	I _C = 1mA, V _{CE} = 10V I _C = 10mA, V _{CE} = 10V I _C = 30mA, V _{CE} = 10V
SMALL SIGNAL CHARACTERISTICS						
Transition Frequency	f _T	50	—	—	MHz	I _C = 10mA, V _{CE} = 20V, f = 100MHz
Output Capacitance	C _{obo}	—	—	3	pF	V _{CB} = 20V, f = 1MHz

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on FR-4 PCB; pad layout as shown on page 4 or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 4. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤ 2%.

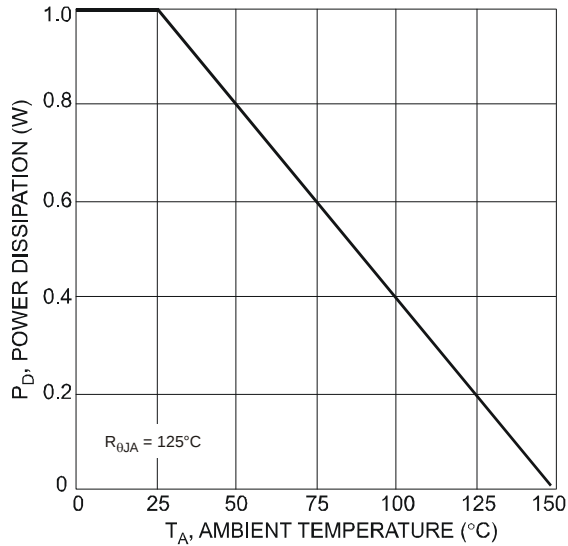


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)

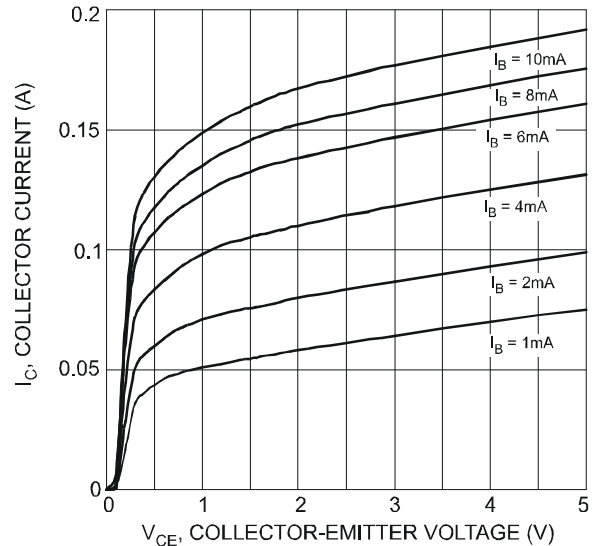


Fig. 2 Collector Current vs. Collector-Emitter Voltage

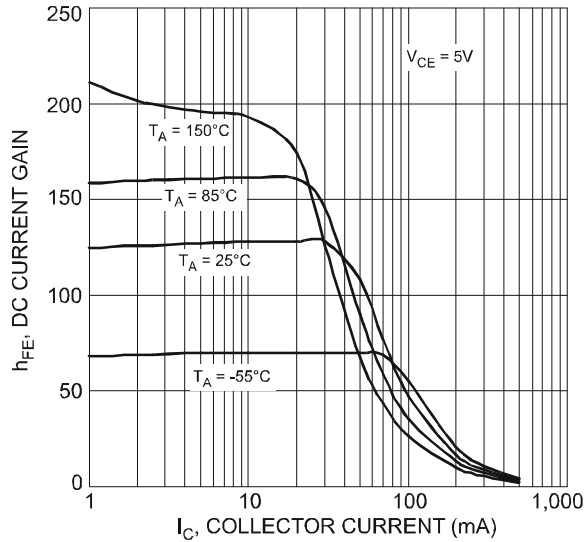


Fig. 3 Typical DC Current Gain vs. Collector Current

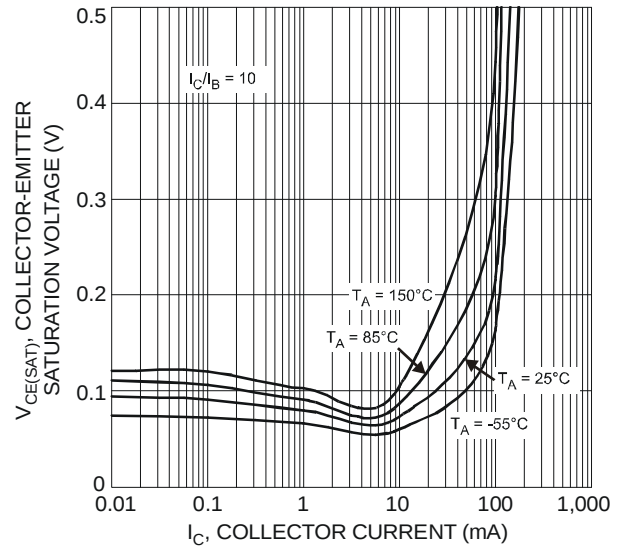


Fig. 4 Collector-Emitter Saturation Voltage vs. Collector Current

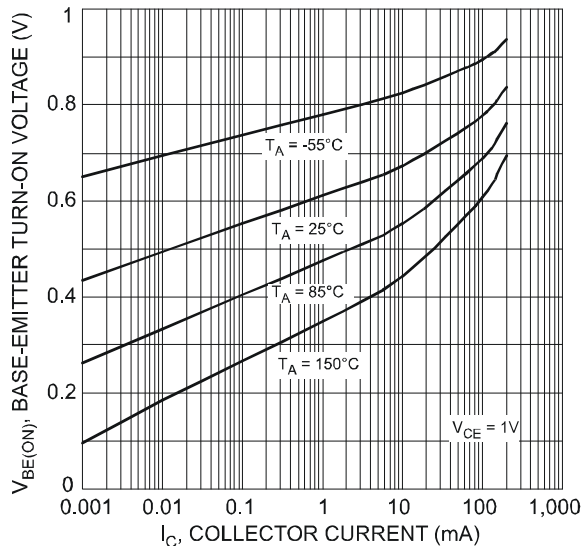


Fig. 5 Base-Emitter Turn-On Voltage vs. Collector Current

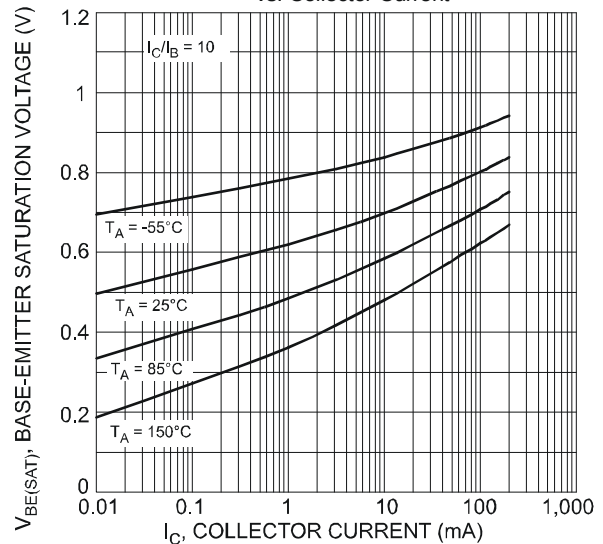


Fig. 6 Base-Emitter Saturation Voltage vs. Collector Current

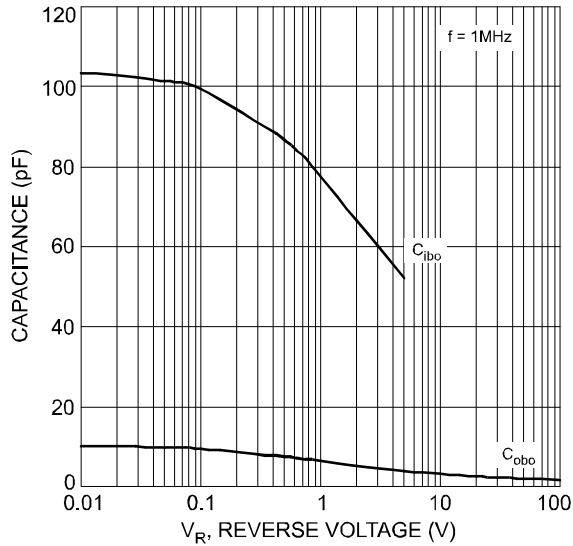


Fig. 7 Typical Capacitance Characteristics

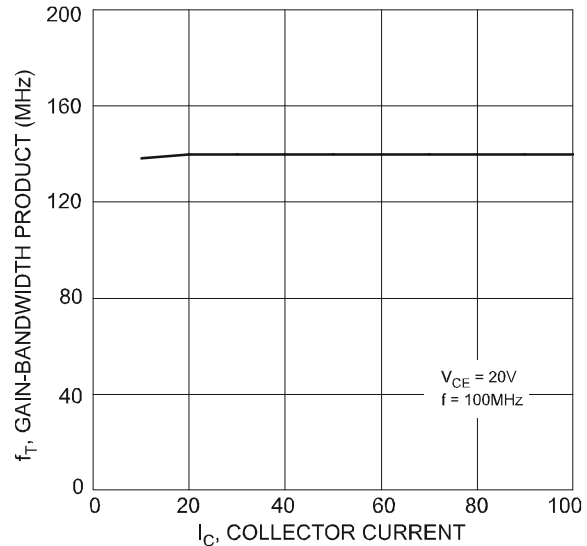


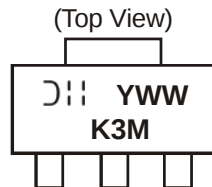
Fig. 8 Gain-Bandwidth Product vs. Collector Current

Ordering Information (Note 5)

Part Number	Case	Packaging
DXTA42-13	SOT89-3L	2500/Tape & Reel

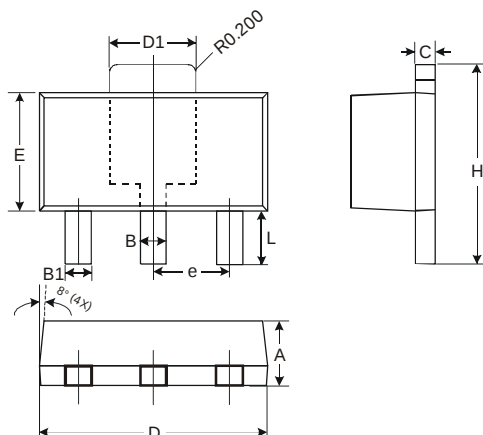
Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



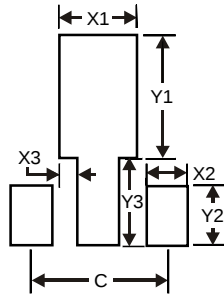
D11 = Manufacturer's code marking
K3M = Product Type Marking Code
YWW = Date Code Marking
Y = Last digit of year ex: 9 = 2009
WW = Week code 01 - 52

Package Outline Dimensions



SOT89-3L			
Dim	Min	Max	Typ
A	1.40	1.60	1.50
B	0.45	0.55	0.50
B1	0.37	0.47	0.42
C	0.35	0.43	0.38
D	4.40	4.60	4.50
D1	1.50	1.70	1.60
E	2.40	2.60	2.50
e	—	—	1.50
H	3.95	4.25	4.10
L	0.90	1.20	1.05
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
X1	1.7
X2	0.9
X3	0.4
Y1	2.7
Y2	1.3
Y3	1.9
C	3.0

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